

IEEE 26th INTERNATIONAL SYMPOSIUM ON THE PHYSICAL AND FAILURE ANALYSIS OF INTEGRATED CIRCUITS

- IPFA 2019 -

02 – 05 July 2019

Grand Hyatt Hotel, Hangzhou, China

6th December 2018

Dear IPFA Supporter

IPFA 2019 CORPORATE SPONSORSHIP PROGRAMME

On behalf of the IPFA 2019 Steering Committee, we would like to invite you to participate in our corporate sponsorship programme for IPFA 2019 to be held from 02 to 05 July 2019 at Hangzhou, China.

The IPFA 2019 Symposium and Exhibition are well established events and are expected to draw close to 300 international participants who are involved in varied critical roles in Integrated Circuit Reliability and Failure Analysis. As such, a corporate sponsorship at IPFA provides a great means to accentuate your brand name and affirm your leading position in this competitive market.

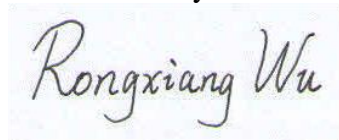
Equally important, this sponsorship programme ensures that IPFA continues to grow and maintains its position as the premier FA and Reliability conference in Asia. This is necessary in order to attract more influential individuals and organizations to the conference to enhance the quality of networking and overall experience at IPFA.

IPFA 2019 will be devoted to the fundamental understanding of the physical mechanisms governing failure in a large variety of advanced semiconductor devices and the electrical - physical failure analysis techniques, methodologies and tools that could be used to reliably identify the root cause of failure in these devices.

We are pleased to attach the details of our sponsorship programmes for your consideration. You are welcome to contact or email us if you have any queries about the sponsorship. The IPFA 2019 Exhibition will be held from 03 – 05 July 2019. The exhibition booth set-up will be on 02 July 2019 (Tuesday), when we will run tutorials conducted by renowned speakers from different parts of the world.

We look forward to your sponsorship participation in IPFA 2019.

Yours sincerely



Rongxiang Wu
Exhibitions/Sponsorship Chair

ORGANIZED BY:



Reliability / Electronics Packaging /
Electron Devices Singapore Chapter

TECHNICALLY CO-SPONSORED BY:



EXHIBITION CHAIR:

No. 28 Hubin Road, Hangzhou
China 310006

Tel: 028-83201281

Email: IPFA2019_Exh@hotmail.com

Website: www.ieee-ipfa.org

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IPFA 2019 SPONSORSHIP PROGRAMME

1. Platinum	USD 18, 000
2. Gold	USD 15, 000
3. Silver	USD 12, 000
4. Banquet	USD 4, 200
5. Conference Bag	USD 3, 500
6. Photo Contest	USD 2, 100
7. Lunch	USD 2, 100
8. Lanyard	USD 1, 400
9. Tea Break	USD 700
10. Publicity Video	USD 1, 200

(co-sponsor with IPFA)

Benefits

• PLATINUM

- 1 free 3m x 3m exhibition booth OR 6 conference passes
- 4 additional conference passes
- Sponsor's name featured in IPFA 2019 Call for papers, website, publicity brochures, conference banners and IPFA 2019 Proceedings/programme
- 2 complimentary nights' stay at Grand Hyatt Hotel

• GOLD

- 1 free 3m x 3m exhibition booth OR 5 conference passes
- 3 additional conference passes
- Sponsor's name featured in IPFA 2019 website, publicity brochures, conference banners and IPFA 2019 Proceedings/programme
- 2 complimentary nights' stay at Grand Hyatt Hotel

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- **SILVER**
 - 1 free 2m x 2m exhibition booth OR 3 conference passes
 - 2 conference passes
 - Sponsor's name featured in IPFA 2019 website, publicity brochures, conference banners and IPFA 2019 Proceeding/programme
 - 1 complimentary night's stay at Grand Hyatt Hotel

 - **BANQUET**
 - Sponsor's name featured at prominent locations during the Banquet

 - **CONFERENCE BAG**
 - Sponsor's company logo featured on the bags

 - **PHOTO CONTEST**
 - Contest will be named after sponsor

 - **LUNCH**
 - Sponsor's name featured at prominent locations during lunch specified

 - **LANYARD**
 - Sponsor's name printed together with IPFA 2019

 - **TEA-BREAK**
 - Sponsor's name featured at prominent locations during tea-break specified
- PUBLICITY VIDEO (co-sponsor with IPFA)**
- Up to 20s of exclusive interview
 - Sponsor's company logo will be featured at the end of the video
 - Visibility at major FA conferences during publicity

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